IEEE P802.11  
Wireless LANs

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| Minutes of the IEEE P802.11 Full Working Group | | | | |
| Date: 2022-05-09 | | | | |
| Author(s): | | | | |
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Abstract

This document constitutes the minutes of the IEEE 802.11 full working group for the May 2022 session.

Please note that all affiliations at this session are shown in Annex A.

**Abbreviations:**

A: Answer

C: Comment

Q: Question

**IEEE 802.11 Interim Session #193**

**May 9th – 17th, 2022**

**IEEE 802.11 Opening Plenary, Monday May 9th 2022**

Presiding chair: Dorothy Stanley (Hewlett Packard Enterprise) opened the meeting at 09:00 Eastern Time (ET) and declared quorum for the session.

1st Vice-chair (VC1): Jon Rosdahl Qualcomm

2nd Vice-chair (VC2): Robert Stacey Intel

Secretary: Stephen McCann Huawei Technologies Co., Ltd

There are 511 Voters and 11 Ex Officio voters of IEEE 802.11\*

There were 325 people present in the meeting.

\*who ask to be recognized as such in the 802.11 voters list.

1. **Notices** (11-22-0578r1 slide #3)
   1. Chair: Please note the information about the meeting decorum.
   2. Are there any members of the press present?
      1. None.
   3. IEEE Staff present
      1. Christy Bahn is the IEEE-SA Staff representative for IEEE 802.11.
   4. Please note that this session requires a registration fee to be paid.
2. **Approve/modify working group agenda** (11-22-0577r3)
   1. This is a summary of the meeting today. Please note the schedule for this session on the separate tab “Schedule”.
   2. The TGbe meetings on Tuesday AM1 and Thursday AM1 are now joint sessions.
   3. Chair: I suggest we approve this agenda.
   4. **Move to approve the agenda 11-22-0577r3 for the Monday opening plenary**
      1. Moved: Marc Emmelmann, 2nd: Allan Jones
      2. No objection to approving by unanimous consent
3. **March 2022 WG Minutes**
   1. **Move to approve the March 2022 WG minutes document 11-22-0443r3**
   2. Moved: Stephen McCann, 2nd: Stuart Kerry
   3. Following neither discussion nor dissent the minutes were approved by unanimous consent.
4. **New Attendees** (11-22-0597r0 slide #4)
   1. Straw Poll:
   2. **Are you a new attendee to IEEE 802.11?**
      1. Yes: 9
      2. No: 123
      3. No answer: 92
   3. There is a new members meeting on Tuesday May 10th at 11:15 ET. This is a tutorial for those new members to learn about IEEE 802.11.
5. **Call for essential Patents** (11-22-0593r1)
   1. The current PatCom rules were read out, including the call for essential patents information, as shown by:
   2. <https://development.standards.ieee.org/myproject/Public/mytools/mob/patut.pdf>
      1. There were no issues raised regarding the call for essential patents.
      2. There was no response to the call for essential patents.
6. **Participation and Attendance** (11-22-0593r1)
   1. The slides about IEEE 802 meeting participation and IEEE SA copyright were also read.
   2. Expected participant behavior was also announced.
   3. VC2: Please note the slide about voting in letter ballots (slide #20) and also the valid abstain response in ballots and also all Voters’ obligations to respond to ballots (slide #21).
7. **Announcements** (11-22-0578r1)
   1. **Liaisons** (slide #4)

Chair: There is 1 incoming liaison from the WBA (Wireless Broadband Alliance) (11-22-0098r0) regarding Device Identification <https://mentor.ieee.org/802.11/dcn/22/11-22-0668-00-0000-liaison-statement-from-wba-re-wi-fi-devices-identification-group.pdf>.

* + 1. This will be considered by TGbh during this session.
    2. Q: The quoted link does not point to the correct liaison
    3. Chair: That will be updated.
  1. **EC and IEEE-SA standard board decisions** (slides #5 and #6)
     1. Chair: The EC and IEEE-SA approved the items on the slides.

1. **Logistics and Key events/activities**
   1. **Working group session documents** (11-22-0578r1 slide #7)
   2. **Joint meetings & reciprocal credit with IEEE 802 groups** (slide #8)
      1. Reminder that there are topics relevant to IEEE 802.11 to be covered in IEEE 802.18, IEEE 802.19, IEEE 802.24, IEEE 802.1 NENDICA Industry Connections Activity and IEEE 802 JTC1 SC.
   3. **M3.3 Other WG meeting plans** (11-22-0592r0 slides #5 to #8)
      1. This slide shows information about other WG meetings, future meetings and logistics during this plenary.
      2. Please use the online schedule at the IEEE 802 website for the online meeting times during this plenary. It can be adjusted to show times in your own time zone.
      3. Please remember to record your attendance for each slot during this plenary, using the IMAT tool: <https://imat.ieee.org/802.11>
   4. **M3.3 Audio Visual Etiquette** (slide #7)
      1. VC1: Please remember this advice when you are presenting during online calls.
   5. **M3.5 Session Registration** (slide #9)
      1. VC1: Please note that paid registration is required for this session. At the moment there are 527 registered people for this May plenary.
      2. Please note that after 60 days, individuals who have not paid their registration fees loose most of their rights, including attending further IEEE 802 meetings. Once they have paid, they can re-attend.
      3. Q: A colleague is trying to register now. He is seeing 2 options “late electronic” and “later registration”. Which option does he choose?
      4. VC1: “late electronic” please. I think that is a bug in the registration problem. For the July mixed-mode meeting this will be more important. Please note that the registration is now open for the July 2022 meeting. The early-bird rate finishes on May 20th 2022.
   6. **M3.6 Recording attendance** (slide #10)
      1. VC1: Please note the rules about recording attendance at each IEEE 802.11 meeting during this plenary.
      2. This IEEE 802.11 session does count towards attendance credit. You will require 9 slots to obtain attendance credit over the next 7 working days.
      3. No questions
2. **Status of all sub-groups** (11-22-0578r1)
   1. **Sub-groups summary** (slide #12)
      1. Chair: This is a review of the current IEEE 802.11 groups. There are 3 PARs that need PAR extension requests this year, P802.11bb, P802.11bc and P802.11bd.
   2. **Sub-Group Officer Status** (slide #15)
      1. Chair: I would like to acknowledge all the assistance from the volunteers mentioned on this slide.
   3. **Summary of Ballots** (slide #18)
      1. This is a list of the IEEE 802.11 ballots since the March 2022 session.
3. **Timelines**
   1. There have been some recent updates to the timeline chart from the TGbb, TGbd and TGbc letter ballot results, together with the recently approved Corrigendum-1 (Cor-1) PAR.
   2. <https://www.ieee802.org/11/Reports/802.11_Timelines.htm>
   3. No questions
4. **Group Summaries** (11-22-0591r1)
   1. Special notes were mentioned for the following groups:
   2. **Editors’ meeting and ANA** (slides #3 & #4)
      1. There is an editors’ meeting later today at 16:00 ET, as per the online schedule. Other topics include the ANA status (11-11-0270r61).
      2. No questions
   3. **ARC SC** (slide #5)
      1. There has been 2 teleconferences since the March 2022 meeting, discussing various architecture topics.
      2. There are two meetings in this session.
      3. No questions
   4. **Coex** **SC** (slide #7)
      1. This standing committee will meet once this session.
      2. No questions
   5. **PAR** **SC** (slide #8)
      1. This group will not meet this week.
      2. No questions
   6. **WNG** (slide #9)
      1. There are 10 presentations planned for this session.
      2. No questions
   7. **JTC1** **SC** (slide #10)
      1. There is 1 meeting during this session.
      2. No questions
   8. **REVme** (slide #13)
      1. The objective for this session is to continue considering comments from the D1.0 letter ballot.
      2. No questions
   9. **TGaz** (slide #14)
      1. The group is progressing work to resolve comments received in the initial SA ballot. There are 7 comments remaining from this ballot.
      2. No questions
   10. **TGbb** (slide #17)
       1. The group hopes to resolve comments from the recently completed D2.0 letter ballot.
       2. No questions.
   11. **TGbc** (slide #18)
       1. The work this session is to start working on comments from the recent re-circulation D3.0 letter ballot.
       2. No questions
   12. **TGbd** (slide #20)
       1. The group is waiting for the initial SA Ballot to complete. The group intends to start work on some of the comment resolutions during this session.
       2. Chair: The SA Ballot could not close on May 5th, as the number of SA Ballot resorts did not meet the 75% threshold. Therefore, the SA Ballot has been extended by 10 days. At the moment, 2 more people need to respond to close the SA Ballot.
       3. No questions
   13. **TGbe** (slide #24)
       1. There have been 20 teleconferences since the March 2022 session.
       2. The intention this session, is to complete the comment collection this week and attempt to move forward with an initial D2.0 letter ballot.
       3. No questions
   14. **TGbf** (slide #26)
       1. There have been 15 teleconference calls since the March 2022 meeting on various topics. D0.1 was release and there is currently a comment collection in progress.
       2. No questions
   15. **TGbh** (slide #30)
       1. There are 4 meetings during this session. The group will address requirements definitions and possibly create D1.0.
       2. A response to the WBA liaison will be worked on this session, together with some other technical development work.
       3. No questions
   16. **TGbi** (slide #31)
       1. There are 3 meetings during this session. The group will address requirements definitions.
       2. No questions.
   17. **ITU ad-hoc** (slide #32)
       1. There have been no recent meetings and there will be no teleconferences this session. There are some ITU related activities occurring in IEEE 802.18 this week.
       2. No questions.
5. **IEEE 802.18 Liaison** (11-22-0632r1)
   1. This document shows the details of the IEEE 802.18 meetings this session.
   2. There will be 2 meetings this session and there are currently 46 voters within the working group.
   3. The call for comments on the “Table of Frequency Ranges” finished with 10 comments received and 2 late comments.
   4. No questions.
6. **IEEE 802.19 Liaison** (11-22-0709r0)
   1. IEEE 802.19 has 53 Voters and there is 1 meeting this session at 16:00 ET today.
   2. No questions.
7. **IEEE 802 Maintenance Status Liaison** (11-22-0705r2)
   1. There are 2 PARs that continue to be reviewed.
   2. C: The ELLA (Evolved Link Layer Architecture) work will also presented at the next IEEE 802 Technical Plenary covering these topics.
8. **Corrigendum-1** (11-22-0648r2)
   1. There were 8 comments that were received on D1.0.
   2. Q: I would like to point out that D2.0 has not been approved by the working group at this stage.
   3. A: Yes.
   4. Q: Can we make changes to D2.0?
   5. A: Yes, through the letter ballot process.
   6. C: The Cor-1 updates the IEEE 802.11-2020 baseline. Then the other amendments are added to IEEE 802.11-2020 and Cor-1.
   7. Chair: D2.0 is useful to have in the members’ area.
9. **TG and SC Officer Elections May 2022** (11-22-0578r1 slide #20)
   1. The TG and SC chairs will be re-affirmed during this May 2022 interim
   2. The TG and SC vice-chairs will be re-elected during this session.
   3. Q: Can they be re-affirmed or is there an option for a challenge.
   4. Chair: At the vice-chair level, yes.
   5. Q: If the TG/SC chair re-affirmed at the WG fails, does the chair choose someone else?
   6. A: Yes.
10. **AoB**
    1. Q: How do I know if I am in a particular SA ballot pool?
    2. Chair: Please have a look at this link: <https://development.standards.ieee.org/myproject-web/app#myballots>
    3. Chair: The TGbd SA Ballot has now reached its threshold and is complete. Thank you for everyone’s help with this.
11. **Recess**
    1. Meeting recessed at 10:58 ET.

**Tuesday, May 17th 2022**

**IEEE 802.11 Closing Plenary**

Call to order at 09:00 Eastern Time (ET) by Dorothy Stanley (HPE).

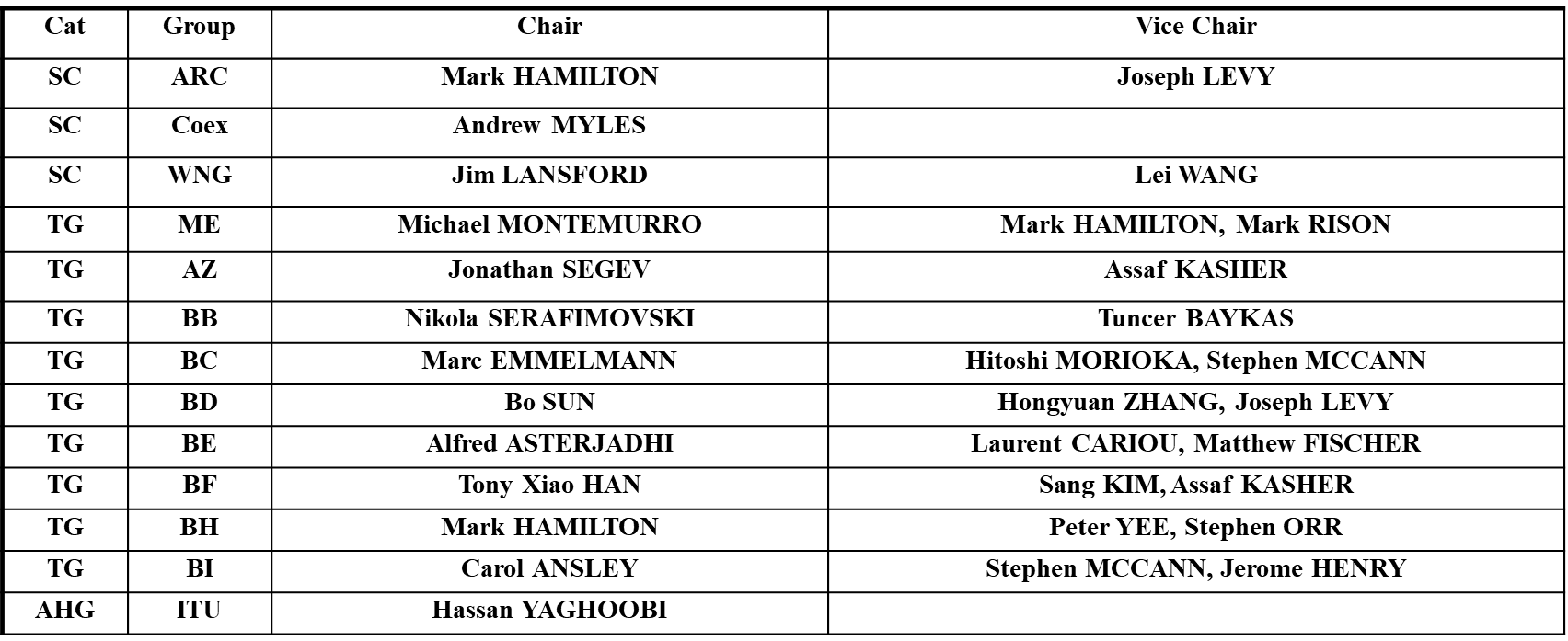
277 people present in the meeting.

1. **Approve/modify working group agenda** (11-22-0577r5)
   1. Chair: There have been some minor changes to the agenda since the opening plenary.
   2. **Approve the agenda for the today’s meeting as shown in 11-22-0577r5**
      1. Moved: Mark Hamilton, 2nd: Stuart Kerry
      2. No objection to approving by unanimous consent.
2. **Announcements** (11-22-0579r0)
   1. **Participation** (slides #4 - #6)
      1. Please can you all remember to read this slide and understand that everyone is here as an individual subject matter expert.
   2. **Call for Essential Patents** (slide #7)
      1. This is the Call for Essential Patents
      2. No statements
      3. No questions.
   3. **Meeting Decorum** (slide #8)
      1. No questions.
   4. **Next session and CAC meetings** (slide #9)
      1. The next session of the IEEE 802.11 working group is from July 11-15th 2022. It will be a mixed mode meeting in Montreal, Canada.
      2. Please be aware of future chair’s committee meetings (CAC), the first one of which will be on June 6th at 09:00 ET. Please note the deadline for the sub-group agendas.
   5. **Sub-group minutes**
      1. Please note that sub-group minutes should be completed within 30 days from the close of this plenary.
   6. **Letters of Assurance (LoA)** (slide #10)
      1. Chair: please remember about the LoA requirements.
      2. There is one LoA request open at the moment.
   7. **IEEE Store and ISO SC6** (slides #11 - #12)
      1. The IEEE 802.11bc draft will be updated to D3.0 shortly.
      2. No questions
      3. The 802.11ax and 802.11ay LoA issues within ISO, are still ongoing.
      4. IEEE 802.11ba-2021 will be submitted after the 11ax related items are resolved.
   8. **Press Releases** (slide #13)
      1. There have been no recent press releases or blog statements.
   9. **IEEE 802 Public Visibility Standing Committee** (slides #14 - #16)
      1. This IEEE 802 group is designed to increase the external visibility of IEEE 802.
      2. There is a planned Tech Talk about IEEE 802 coexistence in June 2022.
      3. There is a link on the slides to the recorded Tech Talks.
3. **Treasury Report** (ec-22-0076-02)
   1. VC1: This shows the treasurers’ report and is correct as of May 1st 2022.
   2. There was 1 deadbeat from the January 2022 session.
   3. The session fees have been increased to cover the additional expense of the mixed-mode tools.
   4. Monies from the September 2021 meeting has now been finalized.
   5. No questions
4. **July & September 2022 Venue Straw Polls** (11-22-0592r0)
   1. T3.1.2 Straw Poll:
      1. **1. The 2022 July Plenary Session is a mixed-mode session with the in person meetings being held in Montreal, Canada will you attend:**
      2. Attend In-person: 81
      3. Attend Virtually (remotely): 85
      4. Will not attend plenary: 11
      5. No response: 54
      6. **2. The 2022 Sept 802 Wireless Interim Session is scheduled to be held at the Waikoloa Hilton in Waikoloa, Hawaii, US, as a mixed-mode session, will you attend?**
      7. Attend In-person: 95
      8. Attend Virtually (remotely): 78
      9. Will not attend interim: 12
      10. No response: 51
5. **Future Venues Manager Report** (11-22-0592r0)
   1. VC1: These slides shows the current status of future venues.
   2. Please note the items to consider for future sessions on slide #14.
   3. The registration page for the July 2022 meeting is already open.
   4. No questions
6. **Timelines**
   1. There are changes to the TGbc, TGbe and TGbh timelines. Changes will be made to the timeline shortly.
   2. No questions.
7. **Attendance statistics** (11-22-0594r1 slide #4)
   1. VC2: These slides are a summary of the attendance statistics and sub-group activities during this session. The numbers have been increasing slowly over the last year or so.
8. **WG Committee Reports** (11-22-0594r1)
   1. **Editors** (slide #10)
      1. No questions.
   2. **ARC SC** (slide #21)
      1. The group continued with the re-structuring of clause 6 discussion.
      2. There are some other future items regarding the IEEE Std 802 revision.
      3. No questions.
   3. **Coex SC** (slide #26)
      1. There were several discussions during the meeting and there is still work to be done going forward regarding Wi-Fi/LAA/NR-U.
      2. They were some additional items about 5 GHz and 6 GHz bands in Europe. There may be some 802.11be coexistence issues with 802.11ax which needs to be studied in more detail within the 5 and 6 GHz bands.
      3. A briefing about IEEE 802.15.4ab needs to be arranged.
      4. Coex SC will meet in hybrid mode in July 2022.
      5. There will be an IEEE 802 Tech Talk on coexistence in June 2022.
      6. No questions.
   4. **WNG** **SC** (slide #30)
      1. There were 10 presentations this session:
         1. “Next Generation after be – follow up”, Laurent Cariou (Intel) 11/0729r1
         2. “Next generation WLAN beyond 11be”, Jinsoo Choi (LG Electronics) 11/0685r0
         3. “Open, Softwarized, Data-Driven 802.11 Networks”, Francesco Restuccia (Northeastern University) 11/0460r3
         4. "Next Gen After 11be v2", Vinko Erceg (Broadcom) 11/0734r0
         5. “Beyond be”, Rolf de Vegt (Qualcomm Technologies, Inc.) 11/0708r0
         6. “Next gen WLAN”, E. Lei (Haier) 11/697r0
         7. “Further discussion on next generation WLAN”, Ming Gan (Huawei) 11/0723r1
         8. “Next Generation WLAN beyond 11be”, Chunyu Hu (Meta) 11/0779r0
         9. “Thoughts on Next Gen WLAN”, Xiaofei Wang (Interdigital) 11/0694r0
         10. “Ambient power enabled IOT for Wi-Fi”, Lei Huang (OPPO) 11/0645r2
      2. No questions.
   5. **JTC1 SC** (slide #33)
      1. At the moment, there are still some IPR issues regarding the IEEE 802.11ax ISO ballot. Until these are resolved, other IEEE 802.11 amendments will not be sent to ISO for adoption under the PSDO agreement. Progress appears to be rather slow.
      2. No questions.
   6. **TGme** (slide #35)
      1. This session continued to resolve comments from LB 258.
      2. There is an ad-hoc planned for August 23-25th in either the UK or US.
      3. No questions.
   7. **TGaz** (slide #40)
      1. The group has completed the comments received from the initial SA Ballot and approved a 15 day re-circulation ballot. Draft 5.0 should be published shortly.
      2. No questions.
   8. **TGbb** (slide #45)
      1. The session has finished resolving comments from the initial letter ballot. There will be a later motion to approve and start a re-circulation letter ballot with D3.0.
      2. No questions.
   9. **TGbc** (slide #49)
      1. The comments from the D3.0 re-circulation ballot were worked on this week.
      2. No questions.
   10. **TGbd** (slide #56)
       1. Comments from the 1st SA Ballot were discussed during the session.
       2. No questions.
   11. **TGbe** (slide #64)
       1. There were 7 conference calls during this session.
       2. The work involved the continuation of CC36 comment resolution and they are all complete. The group hopes to move forward with a D2.0 initial letter ballot.
       3. There will be an ad-hoc meeting in September 7-9th 2022.
       4. No questions.
   12. **TGbf** (slide #67)
       1. There were 3 meetings during this session.
       2. There is an open comment collection on D0.1.
       3. No questions.
   13. **TGbh** (slide #73)
       1. There will be a comment collection on D0.2 for 30 days.
       2. No questions.
   14. **TGbi** (slide #78)
       1. There were discussion about the use cases and issues documents.
       2. No questions.

Chair: The SA Ballot pool for the corrigendum (Cor-1) is now open and closes tomorrow.

In addition the 11bb and 11bc SA Ballot pools also need to be created during July 2022.

1. **Liaison Reports** (11-22-0594r1)
   1. **Wi-Fi Alliance** (slide #84)
      1. There are several certifications based on IEEE 802 programs.
      2. The next meeting will be Chicago in June 2022.
      3. Q: Does “Wi-Fi 6” refer to “Wi-Fi 6E” and “Wi-Fi 6 release 2”.
      4. A: Yes.
      5. Chair: I would like to congratulate Carlos on becoming chairman of the Wi-Fi Alliance board.
   2. **IETF** (slide #88)
      1. The next meeting will be in July 2022 as a hybrid in Philadelphia.
      2. No questions.
   3. **IEEE 1609** (slide #107)
      1. IEEE 1609 provides a light weight middle layer between 802.11p/bd and an upper layer.
      2. No questions.
2. **Potential Break**
   1. Chair: Are members interested in a break now? Majority of responses were yes, so there was a 5 minute break.
3. **Working Group Motions (Old Business)** (11-22-0597r3)
   1. **Motion 1: Officer Confirmation**

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* + 1. Moved: Mike Montemurro, Second: Tuncer Baykas
    2. No objection to approving by unanimous consent (Motion passes)
  1. **Motion 2: Cor-1 Initial Letter Ballot comment**
     1. Approve the resolutions in 11-22/0648r4 for the comments received from LB262.
     2. Moved: Robert Stacey, Second: Jon Rosdahl
     3. No objection to approving by unanimous consent (Motion passes)
  2. **Motion 3: Cor-1 Re-circulation Letter Ballot**
     1. **Having resolved all comments on LB262 in 11-22/0648r4 and the editor having implemented the resolutions in P802.11-2020/Cor1/D2.1, approve a 15 day WG Technical Letter Ballot on P802.11-2020/Cor1/D2.1 asking the question**
     2. **“Should P802.11-2020/Cor1/D2.1 be forwarded to SA ballot?”**
     3. Moved: Robert Stacey, Second: Jon Rosdahl
     4. No objection to approving by unanimous consent (Motion passes)
  3. **Motion 4: Cor-1 SA Ballot**
     1. **Believing that P802.11-2020/Cor1/D2.1 meets the conditions for IEEE 802 SA ballot,**
     2. **• Approve document 11-22/0792r2 as the report to the IEEE 802 Executive Committee on the requirements for approval to forward P802.11-2020/Cor1/D2.1 to SA Ballot, granting the WG chair editorial license, and**
     3. **• Request the IEEE 802 Executive Committee to conditionally forward P802.11-2020/Cor1/D2.1 to SA ballot.**
     4. The VC-2 presented document 11-22/0792r1.
     5. No questions
     6. Moved: Robert Stacey, Second: Jon Rosdahl
     7. Result: Yes: 121, No: 0, Abstain: 26 (Motion passes)
  4. **Motion 5: TIG Re: AI/ML use in 802.11**
     1. **Approve formation of a Topic Interest Group (TIG) to:**
     2. **(a) describe use cases for Artificial Intelligence/Machine Learning (AI/ML) applicability in 802.11 systems and**
     3. **(b) investigate the technical feasibility of features enabling support of AI/ML.**
     4. **The TIG is to complete a report on this topic at or before the March 2023 session.**
     5. Moved: Stephen McCann, Second: Marc Emmelmann
     6. Result: Yes:119, No: 22, Abstain: 27 (Motion passes)
  5. **Motion 6: TIG Re: ambient power IoT devices** 
     1. **Approve formation of a Topic Interest Group (TIG) to:**
     2. **(a) describe use cases for 802.11 ambient power-enabled IoT devices and**
     3. **(b) investigate the technical feasibility of features to enable 802.11 WLAN support of ambient power enabled IoT devices.**
     4. **The TIG is to complete a report on this topic at or before the March 2023 session.**
     5. Moved: Lei Huang, Second: Joseph Levy
     6. Result: Yes: 101, No: 19, Abstain: 41 (Motion passes)
  6. **Motion 7: TGme August 2022 Ad-hoc**
     1. **Approve a TGme ad-hoc meeting on August 23-25, 2022 in US or UK for the purpose of REVme comment resolution and consideration of document submissions.**
     2. Moved: Mike Montemurro, Second: Mark Hamilton
     3. Q: Will this meeting be in mixed mode?
     4. A: Yes
     5. No objection to approving by unanimous consent (Motion passes)
     6. [TG vote result: Unanimous (25 attendees). Passes. [Moved: Jon Rosdahl, Second: Mark Hamilton]
  7. **Motion 8: TGbb PAR extension**
     1. **Believing that the PAR contained in the document referenced below meets IEEE-SA guidelines,**
     2. **Request that the PAR contained in 11-22/0693r0 be posted to the IEEE 802 Executive Committee (EC) agenda for WG 802 preview and EC approval to submit to NesCom.**
     3. Moved by Nikola Serafimovski, Second: Tuncer Baykas
     4. Result: Yes: 99, No: 0, Abstain: 39 (Motion passes)
  8. **Motion 9: TGbb re-circulation letter ballot**
     1. **Having resolved all comments in 11-22/0678r5 and the editor having implemented the resolutions in IEEE 802.11bb D3.0, approve a 15 day WG Technical Letter Ballot on IEEE 802.11bb D3.0 asking the question**
     2. **“Should IEEE 802.11bb D3.0 be forwarded to SA ballot?”**
     3. Moved: Nikola Serafimovski on behalf of TGbb
     4. C: I speak against this motion. The draft doesn’t really show how the PHY and MAC work. The detail in the MAC is not explained in enough detail. I was expecting to see a lot more. 11af produced a similar type of amendment, but in that case the MAC was explained in more detail.
     5. TGbb chair: A lot of these questions have been debated in TGbb. Originally the 11bb amendment was arranged this way and was considerably larger. Following all those discussions and debate, the 11bb amendment has been reduced. Therefore it is the feeling of TGbb that the 11bb D3.0 amendment is indeed implementable.
     6. C: I also speak against the motion. I’ve also provided comments to TGbb about how the MAC can be implemented and I’m not satisfied with the TGbb resolutions.
     7. C: I suggest that the time between now and July is taken by TGbb to add some more detail.
     8. Result: Yes: 45, No: 24, Abstain: 81 (Motion fails)
     9. [TGbb: Moved: Volker Jungnickel, 2nd: Tuncer Baykas, Result: unanimous consent]
  9. **Motion 10: TGbc PAR extension**
     1. **Believing that the PAR contained in the document referenced below meets IEEE-SA guidelines,**
     2. **Request that the PAR contained in 11-22/0692r0 be posted to the IEEE 802 Executive Committee (EC) agenda for WG 802 preview and EC approval to submit to NesCom.**
     3. Moved by Marc Emmelmann, Second: Xiaofei Wang
     4. Result: Yes: 106, No: 0, Abstain: 29 (Motion passes)
     5. [TGbc Moved: Stephen McCann, Seconded: Antonio de la Oliva, Result: 29/0/2]
  10. **Motion 11: TGbd PAR extension**
      1. **Believing that the PAR contained in the document referenced below meets IEEE-SA guidelines,**
      2. **Request that the PAR contained in 11-22/0703r0 be posted to the IEEE 802 Executive Committee (EC) agenda for WG 802 preview and EC approval to submit to NesCom.**
      3. Moved by Bo Sun on behalf of TGbd, Second: Joseph Levy
      4. Result: Yes: 104, No: 0, Abstain: 22 (Motion passes)
      5. [TGbd: Moved: Joseph Levy, 2nd Stephan Sand: Result 12/0/1]
  11. **Motion 12: Liaise IEEE 802.11bd/D4.0 to SC6**
      1. **The IEEE 802.11 WG requests that IEEE 802 EC liaise Draft P802.11bd/D4.0 to ISO/IEC JTC1 SC6 for information.**
      2. Moved by Bo Sun on behalf of TGbd, Seconded: Edward Au
      3. Result: Yes: 100, No: 0, Abstain: 25 (Motion passes)
      4. [TGbd: Moved: Joseph Levy, 2nd Stephan Sand: Result 14/0/0]
  12. **Motion 13: TGbe CAD approval**
      1. **Approve the P802.11be Coexistence Assessment document in 11-21/0706r5.**
      2. Moved: Alfred Asterjadhi on behalf of TGbe, Second: Alecsander Eitan
      3. Result: Yes: 118, No: 1, Abstain: 18 (motion passes)
      4. [TGbe: Moved: Laurent Cariou, 2nd: Stephen McCann, result: 134Y, 3N, 21A]
  13. **Motion 14: TGbe initial letter ballot**
      1. C: I would like some more time to review this document. I suggest 40 days please.
      2. TGbe chair: 40 days should be fine.
      3. Q: Were there any motions related to text changes that were not covered by CIDs. These are text changes without corresponding CIDs.
      4. A: Yes there are. I suggest updating the motion text to reflect this.
      5. **Having approved changes to P802.11be D1.0, as defined in 11-21/1018r64 and motions passed in 11-20/1982r78,**
      6. **Instruct the editor to prepare P802.11be D2.0, and**
      7. **Approve a 40 day Working Group Technical Letter Ballot asking the question “Should P802.11be D2.0 be forwarded to SA Ballot?”**
      8. Moved: Alfred Asterjadhi, Second: Harry Bims
      9. Result: Yes: 145, No: 2, Abstain: 16 (Motion passes)
      10. [TGbe Moved: Bin Tian, Seconded: Mike Montemurro, result: 159Y, 5N, 15A]
      11. Recorded Vote:

|  |  |  |  |
| --- | --- | --- | --- |
| Name/Affiliation | Yes | No | Abstain |
| Jon Rosdahl, Qualcomm | X |  |  |
| Rich Kennedy, SELF | X |  |  |
| Rakesh Taori , Infineon | X |  |  |
| Sang Kim LGE | X |  |  |
| Al Petrick InterDigital |  |  | X |
| Xiaofei Wang InterDigital |  |  | X |
| Allan Jones - Activision | X |  |  |
| Claudio da Silva, Meta | X |  |  |
| Gaurang Naik, Qualcomm Inc. | X |  |  |
| Lili Hervieu CableLabs | X |  |  |
| Ayush, Infineon | X |  |  |
| Mengshi Hu Huawei |  |  | X |
| Chaoming Luo, OPPO |  |  | X |
| Lei Zhou, New H3C Technologies | X |  |  |
| George Chih-Chun Kuo, Mediatek | X |  |  |
| Max Riegel - Nokia | X |  |  |
| Seungho Choo Senscomm | X |  |  |
| Trivikram Gangur, Infineon | X |  |  |
| Jason Yuchen Guo Huawei | X |  |  |
| Rojan Chitrakar Panasonic | X |  |  |
| Bo Sun | X |  |  |
| Ryota Yamada, Sharp | X |  |  |
| Lei Huang OPPO | X |  |  |
| Rajat Pushkarna Panasonic |  |  | X |
| Ross Jian Yu Huawei | X |  |  |
| Yunbo Li Huawei | X |  |  |
| Kazuto Yano ATR | X |  |  |
| Mao Yu Anyka | X |  |  |
| Robert Stacey, Intel | X |  |  |
| John Kenney, Toyota | X |  |  |
| William Carney, Sony Group | X |  |  |
| Jarkko Kneckt, Apple | X |  |  |
| Peter Yee, NSA-CSD | X |  |  |
| Yonggang Fang MediaTek | X |  |  |
| John Yi, SPRD | X |  |  |
| Fumihide Goto, DENSO | X |  |  |
| Mohamed Abouelseoud Apple | X |  |  |
| [HP Inc.] Alan Berkema | X |  |  |
| Noel Stott Keysight Technologies | X |  |  |
| Chunyu | X |  |  |
| Kanke Wu Qualcomm | X |  |  |
| Yong Liu | X |  |  |
| Duncan Ho, Qualcomm | X |  |  |
| Lei Wang Futurewei | X |  |  |
| Meriam Rezk Qualcomm | X |  |  |
| Abhishek Patil Qualcomm | X |  |  |
| Rui Cao [NXP] | X |  |  |
| James Chiang, MediaTek | X |  |  |
| Yujin Noh | X |  |  |
| Chris Levesque - Qorvo | X |  |  |
| Kapil Rai, Qualcomm | X |  |  |
| Dan Bravo, Intel | X |  |  |
| Qi Wang, Apple | X |  |  |
| Binita Gupta, Meta | X |  |  |
| Jianhan Liu, Mediatek | X |  |  |
| Daniel Borges | X |  |  |
| Sigurd Schelstraete MaxLinear | X |  |  |
| Ahmed Elsherif Qualcomm | X |  |  |
| Ron Porat Broadcom | X |  |  |
| Bin Tian Qualcomm | X |  |  |
| Vamsi Amalladinne, Qualcomm | X |  |  |
| Yanjun Sun Qualcomm | X |  |  |
| Assaf Kasher Qualcomm | X |  |  |
| Stephan Sand German Aerospace Center DLR | X |  |  |
| Geert Awater, Qualcomm | X |  |  |
| Halise Turkmen Vestel |  |  | X |
| Menzo Wentink Qualcomm | X |  |  |
| Ilya Levitsky IITP RAS | X |  |  |
| Stephane Baron Canon | X |  |  |
| Shimi Shilo Huawei |  |  | X |
| Jouni Malinen Qualcomm | X |  |  |
| Evgeny Khorov, IITP RAS |  | X |  |
| Alecsander Eitan Qualcomm | X |  |  |
| Mehmet Ali Aygul; Vestel | X |  |  |
| Tuncer Baykas, Kadir Has University | X |  |  |
| Massinissa Lalam, Sagemcom | X |  |  |
| Chong Han pureLiFi |  | X |  |
| Albert Bredewoud | X |  |  |
| Romain GUIGNARD Canon | X |  |  |
| Başak Özbakış, Vestel | X |  |  |
| Arik Klein Huawei | X |  |  |
| Pascal Viger,Canon | X |  |  |
| Richard Van Nee Qualcomm | X |  |  |
| Vyacheslav Loginov, IITP RAS |  |  | X |
| Patrice NEZOU, Canon | X |  |  |
| Antonio de la Oliva Interdigital Ltd. |  |  | X |
| Joerg Robert, TU Ilmenau/Fraunhofer IIS | X |  |  |
| Dong Wei, NXP | X |  |  |
| Sid Thakur [Apple] | X |  |  |
| Dave Halasz, Morse Micro | X |  |  |
| Mike Montemurro Huawei | X |  |  |
| Mahmoud Kamel InterDigital | X |  |  |
| Rolf de Vegt Qualcomm | X |  |  |
| Li-Hsiang Sun Sony | X |  |  |
| Dongguk Lim, LGE | X |  |  |
| Hitoshi Morioka, SRC Software | X |  |  |
| Atsushi Shirakawa, Sharp | X |  |  |
| Jinyoung Chun LGE | X |  |  |
| Jeongki Kim Ofinno | X |  |  |
| Hyeong Ho Lee Netvision Telecom | X |  |  |
| Tetsushi Ikegami\_Meiji Univ. | X |  |  |
| Cheng-Ming Chen Qualcomm | X |  |  |
| HanGyu Cho LGE | X |  |  |
| Greg Geonjung Ko WILUS | X |  |  |
| Jinsoo Choi LG | X |  |  |
| Liuming Lu OPPO | X |  |  |
| Hiroyuki Motozuka, Panasonic | X |  |  |
| Akira Kishida NTT | X |  |  |
| Kengo Nagata NTT | X |  |  |
| Ryuichi Hirata Sony | X |  |  |
| Takuhiro Sato, Sharp | X |  |  |
| SunHee Baek LGE | X |  |  |
| Tomoko Adachi Toshiba | X |  |  |
| Wonjung Kim, LG Uplus | X |  |  |
| Yoshio Urabe, Panasonic | X |  |  |
| Mark Hamilton CommScope/Ruckus | X |  |  |
| Youhan Kim, Qualcomm | X |  |  |
| Jim Lansford Qualcomm | X |  |  |
| Anuj Batra | X |  |  |
| Steve Shellhammer (Qualcomm) | X |  |  |
| Naveen Kakani, Qualcomm | X |  |  |
| Osama Abpul-Magd Huawei | X |  |  |
| John Wullert, Peraton Labs | X |  |  |
| Carol Ansley Cox |  |  | X |
| Hanqing Lou InterDigital |  |  | X |
| Ray Yang, InterDigital |  |  | X |
| Yan Xin Huawei | X |  |  |
| Jung Hoon Suh Huawei | X |  |  |
| Chris Beg, Cognitive Systems |  |  | X |
| Joseph Levy, InterDigital |  |  | X |
| Kurt Lumbatis ,ARRIS/CommScope | X |  |  |
| Edward Au | X |  |  |
| Kiseon Ryu Ofinno | X |  |  |
| Zinan Lin InterDigital | X |  |  |
| Prabodh Varshney Nokia | X |  |  |
| Sundeep Kancherla, Infineon | X |  |  |
| Kunal Lal Synaptics | X |  |  |
| Julien SEVIN Canon | X |  |  |
| David Boldy Broadcom | X |  |  |
| Kirill Chemrov IITP RAS | X |  |  |
| Mickael LORGEOUX Canon | X |  |  |
| laurent cariou, Intel | X |  |  |
| Charlie Pettersson Ericsson | X |  |  |
| Ishaque Kadampot, Qualcomm | X |  |  |
| VK Jones - Qualcomm | X |  |  |
| Matthew Fischer Broadcom | X |  |  |
| Kaiying Lu | X |  |  |
| Muhammad Kumail Haider, Meta | X |  |  |
| Carlos Cordeiro | X |  |  |
| Thomas Pare Mediatek | X |  |  |
| James Yee, MediaTek | X |  |  |
| Po-Kai Huang Intel | X |  |  |
| Shuling Julia Feng, Mediatek | X |  |  |
| Alfred Asterjadhi, Qualcomm Inc. | X |  |  |
| Paul Strauch, Qualcomm | X |  |  |
| Christian Berger, NXP | X |  |  |
| Minyoung Park Intel | X |  |  |
| Lisa Ward - Rohde & Schwarz |  |  | X |
| [Mediatek] Gabor Bajko | X |  |  |
| Srinivas Kandala Samsung | X |  |  |
| Subir Peraton Labs | X |  |  |
| Harry Bims | X |  |  |
| Gaurav Patwardhan HPE |  |  | X |

* + 1. Chair: When will D2.0 be available?
    2. C: A clean D1.6 has just been produced. Over the next few days, this will be tidied up and reviewed by volunteers. Therefore it should be early next week.
    3. Q: Do the CID tags really need to be removed?
    4. A: This is usually done.
    5. C: I can help the TGbe editor to do this.
  1. **Motion 15: TGbe September 2022 Ad-hoc**
     1. **Approve a TGbe ad-hoc meeting on September 7-9th, 2022 in the San Diego, US area for the purpose of TGbe comment resolution and consideration of document submissions.**
     2. Moved by Alfred Asterjadhi on behalf of TGbe
     3. Q: What is the mask policy?
     4. A: Whatever is determined by the local administration
     5. C: It will be a hybrid meeting
     6. Q: Is it possible to move the venue to that of the main IEEE 802.11 interim in Hawaii?
     7. A: I spoke to the 802.11 officers about this and then the TGbe members decided against it. In the future, this would make sense.
     8. Q: Does this mean that there will be fewer TGbe teleconferences between July and September 2022.
     9. TGbe Chair: I expect so.
     10. Q: I attended a European conference last week and I ended up catching Covid-19. Therefore I would to like to mandate mask wearing at our meetings.
     11. A: It’s hard to mandate this. The IEEE 802 EC have debated this and have decided that it should be up to the local jurisdiction to decide what the policy should be.
     12. Result: Yes: 81, No: 26, Abstain: 38 (motion passes)
     13. [TGbe result: 96Y, 18N, 34A]
     14. C: Will the ad-hoc be able to run motions
     15. Chair: The 10 day notice for teleconference applies.
     16. Q: Why no second?
     17. A: The motion was on behalf of the TG and no second is required.
     18. Q: Was that a procedural motion?
     19. Chair: Yes, it was procedural.
     20. Q: Regarding motions in the ad-hoc, it will be difficult for external people to attend the meeting for these motions. Please can motions be held at a specific time?
     21. Chair: Yes, that is reasonable. The guidance for teleconference is that motions are held during hours that are available to everyone globally.

1. **Wireless Chairs Meeting** (11-22-0579r0 slide #16)
   1. The next meeting is on June 1st at 15:00 ET. This meeting will use a tool that is recommend for future hybrid meetings. Please contact the IEEE 802.11 chair or vice-chairs with a request for the registration information, or see the calendar entry.
2. **Next Meeting** (slide #17)
   1. The proposed date of the next IEEE 802.11 meeting is July 10-15th 2022 in Montreal, Canada as a mixed mode meeting.
3. **Any other Business (AoB)**
   1. None
4. **Adjournment**
   1. Having completed the agenda, the chair announced that the meeting was adjourned at 11:34 ET.

**Annex A: Attendance & Affiliation**

| **Name** | **Affiliation** | **Attended >= 75%?** | **Status** |
| --- | --- | --- | --- |
| AbidRabbu, Shaima' | Istanbul Medipol University; Vestel | FALSE | Voter |
| Abouelseoud, Mohamed | Apple Inc. | TRUE | Voter |
| Aboulmagd, Osama | Huawei Technologies Co., Ltd | TRUE | Voter |
| Adachi, Tomoko | TOSHIBA Corporation | TRUE | Voter |
| Adakeja, olubukola | Teradyne, Inc. | TRUE | Aspirant |
| Adhikari, Shubhodeep | Broadcom Corporation | TRUE | Voter |
| Ahmad, Tufail | koc university, vestel | TRUE | Aspirant |
| Aio, Kosuke | Sony Corporation | TRUE | Voter |
| Ajami, Abdel Karim | Qualcomm Incorporated | TRUE | Voter |
| Akhmetov, Dmitry | Intel Corporation | TRUE | Voter |
| Aldana, Carlos | Facebook | TRUE | Voter |
| Amalladinne, Vamsi | Qualcomm Incorporated | TRUE | Voter |
| Andersdotter, Amelia | Sky UK Group | TRUE | Voter |
| Ansley, Carol | Cox Communications Inc. | TRUE | Voter |
| Anwyl, Gary | MediaTek Inc. | TRUE | Voter |
| Asai, Yusuke | NTT | TRUE | Voter |
| Asterjadhi, Alfred | Qualcomm Incorporated | TRUE | Voter |
| Au, Kwok Shum | Huawei Technologies Co., Ltd | TRUE | ExOfficio |
| Au, Oscar | Origin Wireless | TRUE | Voter |
| Avital, Ziv | MaxLinear | TRUE | Voter |
| Awater, Geert | Qualcomm Incorporated | TRUE | Voter |
| Aygul, Mehmet | Vestel | TRUE | Voter |
| Baek, SunHee | LG ELECTRONICS | TRUE | Voter |
| Bahn, Christy | IEEE STAFF | FALSE | Potential Voter |
| Baik, Eugene | Qualcomm Incorporated | TRUE | Voter |
| Bajko, Gabor | MediaTek Inc. | TRUE | Voter |
| Balakrishnan, Hari Ram | NXP Semiconductors | TRUE | Voter |
| Banerjea, Raja | Qualcomm Incorporated | FALSE | Voter |
| Bankov, Dmitry | IITP RAS | TRUE | Voter |
| Baron, stephane | Canon Research Centre France | TRUE | Voter |
| Batra, Anuj | Apple, Inc. | TRUE | Voter |
| Baykas, Tuncer | Kadir Has University, | TRUE | Voter |
| Beg, Chris | Cognitive Systems Corp. | TRUE | Voter |
| Ben Arie, Yaron | Toga networks (a huawei company) | TRUE | Voter |
| Berens, Friedbert | FBConsulting Sarl | TRUE | Voter |
| Berger, Christian | NXP Semiconductors | TRUE | Voter |
| Berkema, Alan | HP Inc. | TRUE | Voter |
| Bims, Harry | Bims Laboratories, Inc. | TRUE | Voter |
| Bluschke, Andreas | Signify | TRUE | Voter |
| Bober, Lennert | Fraunhofer Heinrich Hertz Institute | TRUE | Voter |
| Boldy, David | Broadcom Corporation | TRUE | Voter |
| Borges, Daniel | Apple, Inc. | TRUE | Voter |
| Bravo, Daniel | Intel Corporation | TRUE | Voter |
| Bredewoud, Albert | Broadcom Corporation | TRUE | Voter |
| Burkhardt, Frank | Fraunhofer IIS | TRUE | Aspirant |
| Cao, Rui | NXP Semiconductors | TRUE | Voter |
| Cariou, Laurent | Intel Corporation | TRUE | Voter |
| Carney, William | Sony Group Corporation | TRUE | Voter |
| Carter, Edward | Infineon Technologies | TRUE | Voter |
| Cavalcanti, Dave | Intel Corporation | TRUE | Voter |
| Chang, Chen-Yi | Mediatek | TRUE | Voter |
| Chaplin, Clint | Self | FALSE | ExOfficio |
| Chappell, Matthew | Cox Communications Inc. | TRUE | Potential Voter |
| Chemrov, Kirill | IITP RAS | TRUE | Voter |
| Chen, Cheng | Intel Corporation | TRUE | Voter |
| Chen, Cheng-Ming | Qualcomm Incorporated | TRUE | Voter |
| Chen, Evelyn | Ericsson AB | TRUE | Voter |
| Chen, Xiaogang | Intel Corporation | TRUE | Voter |
| Chen, Yu | ZTE Corporation | FALSE | Non-Voter |
| Cheng, Paul | MediaTek Inc. | TRUE | Voter |
| cheng, phoebe | MediaTek Inc. | TRUE | Potential Voter |
| Cheng, Xilin | NXP Semiconductors | TRUE | Voter |
| CHERIAN, GEORGE | Qualcomm Incorporated | TRUE | Voter |
| Chiang, James | MediaTek Inc. | TRUE | Voter |
| Chitrakar, Rojan | Panasonic Asia Pacific Pte Ltd. | TRUE | Voter |
| Chiu, Lin-Kai | MediaTek Inc. | TRUE | Voter |
| Chiu, WenHsien | MediaTek Inc. | TRUE | Aspirant |
| Chng, Shi Baw | BAWMAN LLC | TRUE | Aspirant |
| Cho, Hangyu | LG ELECTRONICS | TRUE | Voter |
| Choi, Jinsoo | LG ELECTRONICS | TRUE | Voter |
| Choo, Seungho | Senscomm Semiconductor Co., Ltd. | TRUE | Voter |
| Chu, Liwen | NXP Semiconductors | TRUE | Voter |
| CHUN, JINYOUNG | LG ELECTRONICS | TRUE | Voter |
| Chung, Bruce | Realtek Semiconductor Corp. | TRUE | Voter |
| Chung, Chulho | SAMSUNG | TRUE | Voter |
| Coffey, John | Realtek Semiconductor Corp. | TRUE | Voter |
| Cordeiro, Carlos | Intel Corporation | TRUE | Voter |
| da Silva, Claudio | Meta Platforms, Inc. | TRUE | Voter |
| Das, Dibakar | Intel Corporation | TRUE | Voter |
| Das, Subir | Peraton Labs | TRUE | ExOfficio |
| Dash, Debashis | Apple, Inc. | TRUE | Voter |
| Dave, Brajesh | Apple, Inc. | TRUE | Aspirant |
| de Vegt, Rolf | Qualcomm Incorporated | TRUE | Voter |
| DeLaOlivaDelgado, Antonio | InterDigital, Inc. | TRUE | Voter |
| Derham, Thomas | Broadcom Corporation | TRUE | Voter |
| DESMOULIN, Patrice | Orange | TRUE | Potential Voter |
| Ding, Yanyi | Panasonic corporation | TRUE | Voter |
| Dogukan, Ali | Vestel | TRUE | Voter |
| Dong, mingjie | Huawei Technologies Co., Ltd | TRUE | Voter |
| Dong, Xiandong | Xiaomi Inc. | TRUE | Voter |
| Du, Rui | Huawei Technologies Co., Ltd | TRUE | Voter |
| Du, Zhenguo | Huawei Technologies Co., Ltd | TRUE | Voter |
| Duan, Ruchen | SAMSUNG | TRUE | Voter |
| Ecclesine, Peter | Cisco Systems, Inc. | TRUE | Voter |
| Eitan, Alecsander | Qualcomm Incorporated | TRUE | Voter |
| ElSherif, Ahmed | Qualcomm Incorporated | TRUE | Voter |
| Emmelmann, Marc | Self Employed / Koden-TI / Fraunhofer FOKUS | TRUE | Voter |
| Erceg, Vinko | Broadcom Corporation | TRUE | Voter |
| Erkucuk, Serhat | Ofinno | TRUE | Potential Voter |
| Fang, Juan | Intel Corporation | TRUE | Voter |
| Fang, Yonggang | MediaTek Inc. | TRUE | Voter |
| Fazel, Fatemeh | Intel Corporation | FALSE | Non-Voter |
| feng, Shuling | MediaTek Inc. | TRUE | Voter |
| Fischer, Matthew | Broadcom Corporation | TRUE | Voter |
| Fletcher, Paul | Samsung Cambridge Solution Centre | TRUE | Voter |
| Frotzscher, Andreas | Fraunhofer IIS | TRUE | Aspirant |
| Gan, Ming | Huawei Technologies Co., Ltd | TRUE | Voter |
| Gangur, Trivikram | Infineon Technologies | TRUE | Voter |
| Gao, Ning | Guangdong OPPO Mobile Telecommunications Corp.,Ltd | TRUE | Potential Voter |
| Gee, Thomas | Qorvo | TRUE | Aspirant |
| Ghaderipoor, Alireza | MediaTek Inc. | TRUE | Voter |
| Ghosh, Chittabrata | Meta | TRUE | Voter |
| Gidvani, Ravi | SAMSUNG ELECTRONICS | TRUE | Voter |
| Godbole, sachin | Broadcom Corporation | TRUE | Voter |
| Godfrey, Tim | Electric Power Research Institute, Inc. (EPRI) | FALSE | ExOfficio |
| Gong, Bo | Huawei Technologies Co., Ltd | TRUE | Voter |
| Gorthi, Hemamali | Infineon Technologies | TRUE | Aspirant |
| GOTO, Fumihide | DENSO | TRUE | Voter |
| Grandhe, Niranjan | NXP Semiconductors | TRUE | Voter |
| Gu, Xiangxin | UNISOC | TRUE | Voter |
| GUIGNARD, Romain | Canon Research Centre France | TRUE | Voter |
| Guo, Jing | NXP Semiconductors | TRUE | Voter |
| Guo, Yuchen | Huawei Technologies Co., Ltd | TRUE | Voter |
| Gupta, Binita | Meta Platforms, Inc. | TRUE | Voter |
| gutierrez, luis | Broadcom Corporation | TRUE | Aspirant |
| Haasz, Jodi | IEEE Standards Association (IEEE-SA) | FALSE | Non-Voter |
| Haider, Muhammad Kumail | Facebook | TRUE | Voter |
| Halasz, David | Morse Micro | TRUE | Voter |
| Hamilton, Mark | Ruckus/CommScope | TRUE | Voter |
| HAN, CHONG | pureLiFi | TRUE | Voter |
| Han, Jonghun | SAMSUNG | TRUE | Voter |
| HAN, Xiao | Huawei Technologies Co., Ltd | TRUE | Voter |
| Han, Zhiqiang | ZTE Corporation | TRUE | Voter |
| Handte, Thomas | Sony Group Corporation | TRUE | Voter |
| Harkins, Daniel | Aruba Networks, Inc. | TRUE | Voter |
| Harrison, Edward | Anritsu Company | TRUE | Voter |
| Hart, Brian | Cisco Systems, Inc. | TRUE | Voter |
| Hawkes, Philip | Qualcomm Incorporated | FALSE | Non-Voter |
| Henry, Jerome | Cisco Systems, Inc. | TRUE | Voter |
| Hernandez, Marco | National Institute of Information and Communications Technology (NICT) | FALSE | Voter |
| hervieu, Lili | Cable Television Laboratories Inc. (CableLabs) | TRUE | Voter |
| Hiertz, Guido | Ericsson GmbH | TRUE | Voter |
| Hirata, Ryuichi | Sony Group Corporation | TRUE | Voter |
| Ho, Duncan | Qualcomm Incorporated | TRUE | Voter |
| Hsieh, Hung-Tao | MediaTek Inc. | TRUE | Voter |
| Hsu, Chien-Fang | MediaTek Inc. | TRUE | Voter |
| Hsu, Ostrovsky | Xiaomi Inc. | TRUE | Potential Voter |
| Hu, Chunyu | Facebook | TRUE | Voter |
| Hu, Mengshi | Huawei Technologies Co., Ltd | TRUE | Voter |
| Hu, Shengquan | MediaTek Inc. | TRUE | Potential Voter |
| HUANG, CHIHAN | MediaTek Inc. | TRUE | Potential Voter |
| Huang, Guogang | Huawei Technologies Co., Ltd | TRUE | Voter |
| Huang, Lei | Guangdong OPPO Mobile Telecommunications Corp.,Ltd | TRUE | Voter |
| Huang, Po-Kai | Intel Corporation | TRUE | Voter |
| Huang, Qisheng | ZTE Corporation | TRUE | Voter |
| Huq, Kazi Mohammed Saidul | Ofinno | TRUE | Potential Voter |
| Hwang, Sung Hyun | Electronics and Telecommunications Research Institute (ETRI) | TRUE | Voter |
| Ibrahim, Ahmed | Samsung Research America | TRUE | Voter |
| Ikegami, Tetsushi | Meiji University | TRUE | Voter |
| Jang, Insun | LG ELECTRONICS | TRUE | Voter |
| Jeffries, Timothy | Futurewei Technologies | TRUE | Voter |
| Jeon, Eunsung | SAMSUNG ELECTRONICS | TRUE | Voter |
| Ji, Chenhe | Huawei Technologies Co., Ltd | TRUE | Voter |
| Jia, Jia | Huawei Technologies Co., Ltd | TRUE | Voter |
| jiang, feng | Apple, Inc. | TRUE | Voter |
| Jiang, Jinjing | Apple, Inc. | TRUE | Voter |
| Jones, Allan | Activision | TRUE | Voter |
| Jones, Vincent Knowles IV | Qualcomm Incorporated | TRUE | Voter |
| Juarez, Jorge | Fraunhofer IIS | TRUE | Aspirant |
| Jung, Insik | LG ELECTRONICS | TRUE | Voter |
| Jungnickel, Volker | Fraunhofer Heinrich Hertz Institute | TRUE | Voter |
| Kadampot, Ishaque Ashar | Qualcomm Technologies, Inc. | TRUE | Voter |
| Kakani, Naveen | Qualcomm Incorporated | TRUE | Voter |
| Kamel, Mahmoud | InterDigital, Inc. | TRUE | Voter |
| Kancherla, Sundeep | Infineon Technologies | TRUE | Voter |
| Kandala, Srinivas | SAMSUNG | TRUE | Voter |
| Kang, HaoHua | MediaTek Inc. | TRUE | Voter |
| KANG, Kyu-Min | Electronics and Telecommunications Research Institute (ETRI) | TRUE | Voter |
| Karmuchi, Shailender | SAMSUNG ELECTRONICS | TRUE | Aspirant |
| Kasargod, Sudhir | Infineon Technologies | TRUE | Voter |
| Kasher, Assaf | Qualcomm Incorporated | TRUE | Voter |
| Katla, satyanarayana | InterDigital, Inc. | TRUE | Potential Voter |
| Kennedy, Richard | IEEE member / Self Employed | TRUE | Voter |
| Kenney, John | Toyota Motor North America | TRUE | Voter |
| Kerry, Stuart | OK-Brit; Self | TRUE | Voter |
| Khan, Naseem | Leidos Engineering. LLC | TRUE | Potential Voter |
| Khorov, EVGENY | IITP RAS | TRUE | Voter |
| Kim, Jeongki | Ofinno | TRUE | Voter |
| kim, Jiin | LG ELECTRONICS | FALSE | Voter |
| Kim, Myeong-Jin | SAMSUNG | FALSE | Voter |
| Kim, Sang Gook | LG ELECTRONICS | TRUE | Voter |
| Kim, Sanghyun | WILUS Inc. | TRUE | Voter |
| Kim, Wonjung | LG Uplus | TRUE | Voter |
| Kim, Yongho | Korea National University of Transportation | TRUE | Voter |
| Kim, Youhan | Qualcomm Incorporated | TRUE | Voter |
| Kipness, Michael | IEEE Standards Association (IEEE-SA) | FALSE | Non-Voter |
| Kishida, Akira | Nippon Telegraph and Telephone Corporation (NTT) | TRUE | Voter |
| Kitazawa, Shoichi | Muroran IT | TRUE | Voter |
| Klein, Arik | Huawei Technologies Co., Ltd | TRUE | Voter |
| KNECKT, JARKKO | Apple, Inc. | TRUE | Voter |
| Ko, Geonjung | WILUS Inc. | TRUE | Voter |
| Kota, Prashant | Infineon Technologies | TRUE | Voter |
| Koundourakis, Michail | Samsung Cambridge Solution Centre | TRUE | Voter |
| Kumari, Warren | Google | TRUE | Potential Voter |
| Kuo, Chih-Chun | MediaTek Inc. | TRUE | Voter |
| Kureev, Aleksey | IITP RAS | TRUE | Voter |
| Lal, Kunal | Synaptics Incorporated | TRUE | Voter |
| Lalam, Massinissa | SAGEMCOM SAS | TRUE | Voter |
| Lan, Zhou | Apple Inc. | TRUE | Voter |
| Lanante, Leonardo | Ofinno | TRUE | Voter |
| Lansford, James | Qualcomm Incorporated; University of Colorado at Boulder | TRUE | Voter |
| Le Houerou, Brice | Canon Research Centre France | TRUE | Voter |
| Lee, Hyeong Ho | Netvision Telecom Inc. | TRUE | Voter |
| Lee, Nancy | Signify | TRUE | Voter |
| Lee, Wookbong | SAMSUNG | TRUE | Voter |
| Lei, E | Haier Group Corporation | FALSE | Non-Voter |
| Levesque, Chris | qorvo | TRUE | Voter |
| Levitsky, Ilya | IITP RAS | TRUE | Voter |
| Levy, Joseph | InterDigital, Inc. | TRUE | Voter |
| Li, Bo | Northwestern Polytechnical University | TRUE | Voter |
| Li, Jialing | Qualcomm Technologies, Inc. | TRUE | Voter |
| Li, Qinghua | Intel Corporation | TRUE | Voter |
| Li, Yan | ZTE Corporation | TRUE | Voter |
| Li, Yapu | Guangdong OPPO Mobile Telecommunications Corp.,Ltd | TRUE | Potential Voter |
| Li, Yiqing | Huawei Technologies Co., Ltd | TRUE | Voter |
| Li, Yunbo | Huawei Technologies Co., Ltd | TRUE | Voter |
| Lim, Dong Guk | LG ELECTRONICS | TRUE | Voter |
| Lin, Hsin-De | MediaTek Inc. | TRUE | Voter |
| Lin, Wei | Huawei Technologies Co., Ltd | TRUE | Voter |
| Lin, Yousi | Huawei Technologies Co., Ltd | TRUE | Voter |
| Lin, Zinan | InterDigital, Inc. | TRUE | Voter |
| Lindskog, Erik | SAMSUNG | TRUE | Voter |
| LIU, CHENCHEN | Huawei Technologies Co., Ltd | TRUE | Voter |
| Liu, Der-Zheng | Realtek Semiconductor Corp. | TRUE | Voter |
| Liu, Jianhan | MediaTek Inc. | FALSE | Voter |
| Liu, Ying | NXP Semiconductors | TRUE | Voter |
| Liu, Yong | Apple, Inc. | TRUE | Voter |
| Liu, Zhiqun | Qualcomm Incorporated | TRUE | Aspirant |
| Loginov, Vyacheslav | IITP RAS | TRUE | Voter |
| Lopez, Miguel | Ericsson AB | TRUE | Voter |
| Lorgeoux, Mikael | Canon Research Centre France | TRUE | Voter |
| Lou, Hanqing | InterDigital, Inc. | TRUE | Voter |
| Lou, Hui-Ling | NXP Semiconductors | TRUE | Voter |
| Lu, Kaiying | MediaTek Inc. | TRUE | Voter |
| Lu, Liuming | Guangdong OPPO Mobile Telecommunications Corp.,Ltd | TRUE | Voter |
| Lumbatis, Kurt | CommScope, Inc. | TRUE | Voter |
| Luo, Chaoming | Beijing OPPO telecommunications corp., ltd. | TRUE | Voter |
| Ma, Li | MediaTek Inc. | TRUE | Voter |
| Ma, Mengyao | Huawei Technologies Co., Ltd | TRUE | Voter |
| Madpuwar, Girish | Broadcom Corporation | TRUE | Voter |
| Malinen, Jouni | Qualcomm Incorporated | TRUE | Voter |
| Mano, Hiroshi | Koden Techno Info K.K. | FALSE | Voter |
| Max, Sebastian | Ericsson AB | TRUE | Voter |
| McCann, Stephen | Huawei Technologies Co., Ltd | TRUE | Voter |
| Mehrnoush, Morteza | Facebook | TRUE | Voter |
| MELZER, Ezer | Toga Networks, a Huawei company | TRUE | Voter |
| Memisoglu, Ebubekir | Istanbul Medipol University; Vestel | TRUE | Voter |
| Minotani, Jun | Panasonic Corporation | TRUE | Voter |
| Mirfakhraei, Khashayar | Zeku | FALSE | Voter |
| Mohanty, Bibhu | Qualcomm Incorporated | TRUE | Voter |
| Monajemi, Pooya | Cisco Systems, Inc. | FALSE | Voter |
| Montemurro, Michael | Huawei Technologies Co., Ltd | TRUE | Voter |
| Morioka, Hitoshi | SRC Software | TRUE | Voter |
| Motozuka, Hiroyuki | Panasonic Holdings Corporation | TRUE | Voter |
| Mukkapati, Lakshmi Narayana | Wi-Fi Alliance | TRUE | Aspirant |
| Mutgan, Okan | Nokia | TRUE | Potential Voter |
| Myles, Andrew | Cisco Systems, Inc. | TRUE | Voter |
| nagata, kengo | Nippon Telegraph and Telephone Corporation (NTT) | TRUE | Voter |
| Naik, Gaurang | Qualcomm Incorporated | TRUE | Voter |
| Nam, Junyoung | Qualcomm Incorporated | TRUE | Voter |
| Namboodiri, Vamadevan | SAMSUNG ELECTRONICS | TRUE | Voter |
| Nandagopalan, SAI SHANKAR | Synaptics | TRUE | Voter |
| Narengerile, Narengerile | Huawei Technologies Co., Ltd | TRUE | Potential Voter |
| Nayak, Peshal | Samsung Research America | TRUE | Voter |
| Nezou, Patrice | Canon Research Centre France | TRUE | Voter |
| Ng, Boon Loong | Samsung Research America | TRUE | Voter |
| Nguyen, An | DHS/CISA | TRUE | Voter |
| Noh, Yujin | Senscomm | TRUE | Voter |
| Ohtsuka, Hiroto | Sony Corporation | FALSE | Non-Voter |
| Omar, Hassan | Huawei Technologies Co., Ltd | TRUE | Voter |
| Orr, Stephen | Cisco Systems, Inc. | TRUE | Voter |
| Ozbakis, Basak | VESTEL Electronics Corp. | TRUE | Voter |
| OZDEN ZENGIN, OZLEM | VESTEL | FALSE | Voter |
| Palayur, Saju | Maxlinear Inc | TRUE | Voter |
| Palm, Stephen | Broadcom Corporation | TRUE | Voter |
| Pare, Thomas | MediaTek Inc. | TRUE | Voter |
| Park, Eunsung | LG ELECTRONICS | TRUE | Voter |
| Park, Minyoung | Intel Corporation | TRUE | Voter |
| Park, Sungjin | Senscomm | TRUE | Aspirant |
| Parsons, Glenn | Ericsson AB | FALSE | ExOfficio |
| Patil, Abhishek | Qualcomm Incorporated | TRUE | Voter |
| Patwardhan, Gaurav | Hewlett Packard Enterprise | TRUE | Voter |
| Peng, Lan | Huawei Technologies Co., Ltd | TRUE | Voter |
| Peng, Ronny | MediaTek Inc. | TRUE | Potential Voter |
| Perahia, Eldad | Hewlett Packard Enterprise | TRUE | Voter |
| Petrick, Albert | InterDigital, Inc. | TRUE | Voter |
| Petry, Brian | Broadcom Corporation | TRUE | Voter |
| Pettersson, Charlie | Ericsson AB | TRUE | Voter |
| Pirhonen, Riku | NXP Semiconductors | TRUE | Voter |
| Porat, Ron | Broadcom Corporation | TRUE | Voter |
| Powell, Clinton | Meta | FALSE | ExOfficio |
| Prabhakaran, Dinakar | Broadcom Corporation | TRUE | Voter |
| Pulikkoonattu, Rethnakaran | Broadcom Corporation | TRUE | Potential Voter |
| Pushkarna, Rajat | Panasonic Asia Pacific Pte Ltd. | TRUE | Voter |
| Qi, Emily | Intel Corporation | TRUE | Voter |
| Rafique, Saira | Istanbul Medipol University, Vestel | TRUE | Voter |
| Rai, Kapil | Qualcomm Incorporated | TRUE | Voter |
| Raissinia, Alireza | Qualcomm Incorporated | TRUE | Voter |
| Rantala, Enrico-Henrik | Zeku | TRUE | Voter |
| Ratnam, Vishnu | Samsung Research America | TRUE | Voter |
| Redlich, Oded | Huawei Technologies Co., Ltd | TRUE | Voter |
| Rege, Kiran | Perspecta Labs | TRUE | Voter |
| Regev, Dror | Toga Networks (a Huawei Company) | TRUE | Voter |
| REICH, MOR | Huawei Technologies Co., Ltd | TRUE | Voter |
| Rezk, Meriam | Qualcomm Incorporated | TRUE | Voter |
| Riegel, Maximilian | Nokia | TRUE | Voter |
| Rison, Mark | Samsung Cambridge Solution Centre | TRUE | Voter |
| Robert, Joerg | TU Ilmenau, Fraunhofer IIS | TRUE | Voter |
| Rodine, Craig | Electric Power Research Institute, Inc. (EPRI) | TRUE | Aspirant |
| Rolfe, Benjamin | Blind Creek Associates | FALSE | Voter |
| Rosdahl, Jon | Qualcomm Technologies, Inc. | TRUE | Voter |
| Roy, Sayak | NXP Semiconductors | TRUE | Voter |
| Ryu, Kiseon | Ofinno | TRUE | Voter |
| Sahoo, Anirudha | National Institute of Standards and Technology | FALSE | Potential Voter |
| Salem, Mohamed | Huawei Technologies Co., Ltd | TRUE | Voter |
| Salman, Hanadi | Istanbul Medipol University; VESTEL | TRUE | Voter |
| Sambasivan, Sam | AT&T | TRUE | Voter |
| Sand, Stephan | German Aerospace Center (DLR) | TRUE | Voter |
| Sandhu, Shivraj | Qualcomm Incorporated | TRUE | Voter |
| Sato, Takuhiro | SHARP CORPORATION | TRUE | Voter |
| Satrasala, Rajeshwari | NXP Semiconductors | TRUE | Voter |
| Schelstraete, Sigurd | Maxlinear | TRUE | Voter |
| Schmidhammer, Martin | German Aerospace Center (DLR) | TRUE | Voter |
| Segev, Jonathan | Intel Corporation | TRUE | Voter |
| Seo, Sangho | Infineon Technologies | TRUE | Voter |
| Seok, Yongho | MediaTek Inc. | TRUE | Voter |
| Serafimovski, Nikola | pureLiFi | FALSE | Voter |
| Sethi, Ankit | NXP Semiconductors | TRUE | Voter |
| Sevin, Julien | Canon Research Centre France | TRUE | Voter |
| Shafin, Rubayet | Samsung Research America | TRUE | Voter |
| Shah, Kunal | Apple Inc. | TRUE | Voter |
| Shaw, Amit | Infineon Technologies | TRUE | Voter |
| Shellhammer, Stephen | Qualcomm Incorporated | TRUE | ExOfficio |
| Shen, Xiaoman | Huawei Technologies Co., Ltd | TRUE | Voter |
| Sherlock, Ian | Texas Instruments Inc. | TRUE | Voter |
| Shilo, Shimi | Huawei Technologies Co., Ltd | TRUE | Voter |
| Shirakawa, Atsushi | SHARP CORPORATION | TRUE | Voter |
| Shu, Tongxin | Huawei Technologies Co., Ltd | TRUE | Aspirant |
| Smith, Graham | SR Technologies | TRUE | Voter |
| Smith, Luther | Cable Television Laboratories Inc. (CableLabs) | TRUE | Potential Voter |
| Son, Ju-Hyung | WILUS Inc. | FALSE | Voter |
| Song, Hao | Intel Corporation | TRUE | Voter |
| Sood, Ayush | Infineon Technologies | TRUE | Voter |
| Sosack, Robert | Molex Incorporated | TRUE | Voter |
| Srinivasa, Sudhir | NXP Semiconductors | TRUE | Voter |
| Srivatsa, Veena | Synaptics; Synaptics Incorporated | TRUE | Potential Voter |
| Stacey, Robert | Intel Corporation | TRUE | Voter |
| Stanley, Dorothy | Hewlett Packard Enterprise | TRUE | Voter |
| Stavridis, Athanasios | Ericsson AB | TRUE | Voter |
| Stott, Noel | Keysight Technologies | TRUE | Voter |
| Strauch, Paul | Qualcomm Incorporated | TRUE | Voter |
| SU, HONGJIA | Huawei Technologies Co., Ltd | TRUE | Voter |
| Suh, JUNG HOON | Huawei Technologies Co., Ltd | TRUE | Voter |
| Sun, Bo | ZTE Corporation | TRUE | Voter |
| Sun, Li-Hsiang | Sony Corporation | TRUE | Voter |
| Sun, Yanbin | Huawei Technologies Co., Ltd | TRUE | Aspirant |
| Sun, Yanjun | Qualcomm Incorporated | TRUE | Voter |
| Sundman, Dennis | Ericsson AB | TRUE | Voter |
| SURACI, FRANK | U.S. Department of Homeland Security | TRUE | Voter |
| Szott, Szymon | AGH University of Science and Technology | TRUE | Potential Voter |
| Takai, Mineo | Space-Time Engineering | TRUE | Voter |
| Tanaka, Yusuke | Sony Group Corporation | TRUE | Voter |
| Taori, Rakesh | Infineon Technologies | TRUE | Voter |
| Thakore, Darshak | Cable Television Laboratories Inc. (CableLabs) | TRUE | Aspirant |
| Thakur, Sidharth | Apple, Inc. | FALSE | Voter |
| Thota, Sri Ramya | Infineon Technologies | TRUE | Voter |
| THOUMY, Francois | Canon Research Centre France | TRUE | Voter |
| Tian, Bin | Qualcomm Incorporated | TRUE | Voter |
| Tolpin, Alexander | Intel Corporation | TRUE | Voter |
| Torab Jahromi, Payam | Facebook | TRUE | Voter |
| Trainin, Solomon | Qualcomm Incorporated | TRUE | Voter |
| Tsai, Tsung-Han | MediaTek Inc. | TRUE | Voter |
| Tsodik, Genadiy | Huawei Technologies Co., Ltd | TRUE | Voter |
| TU, Chunjiang | Bestechnic INC. | TRUE | Potential Voter |
| Tugtekin, Omer | VESTEL Electronics Corp. | TRUE | Potential Voter |
| Turkmen, Halise | Vestel | TRUE | Voter |
| Uln, Kiran | Infineon Technologies | TRUE | Voter |
| Urabe, Yoshio | Panasonic Holdings Corporation | TRUE | Voter |
| Van Nee, Richard | Qualcomm Incorporated | TRUE | Voter |
| Van Zelst, Allert | Qualcomm Incorporated | TRUE | Voter |
| Varshney, Prabodh | Nokia | TRUE | Voter |
| Verenzuela, Daniel | Sony Corporation | TRUE | Voter |
| Verma, Lochan | Apple, Inc. | TRUE | Voter |
| Verma, Sindhu | Broadcom Corporation | TRUE | Voter |
| Vermani, Sameer | Qualcomm Incorporated | TRUE | Voter |
| VIGER, Pascal | Canon Research Centre France | TRUE | Voter |
| Wang, Chao Chun | MediaTek Inc. | TRUE | Voter |
| Wang, Hejun | Haier Group Corporation | FALSE | Non-Voter |
| Wang, Huizhao | Quantenna Communications, Inc. | TRUE | Voter |
| Wang, Lei | Futurewei Technologies | TRUE | Voter |
| Wang, Qi | Apple, Inc. | TRUE | Voter |
| wang, shao-cheng | Amazon, Inc | TRUE | Potential Voter |
| Wang, Steven Qi | Huawei Technologies Co., Ltd | TRUE | Voter |
| Wang, Xiaofei | InterDigital, Inc. | TRUE | Voter |
| Wang, Yi | Huawei Technologies Co., Ltd | FALSE | Non-Voter |
| Wang, Zisheng | ZTE Corporation | TRUE | Voter |
| Want, Roy | Google | TRUE | Voter |
| Ward, Lisa | Rohde & Schwarz | TRUE | Voter |
| Wei, Dong | NXP Semiconductors | TRUE | Voter |
| Wen, Yaxin | Haier Group Corporation | FALSE | Non-Voter |
| Wendt, Matthias | Signify | TRUE | Voter |
| Wentink, Menzo | Qualcomm Incorporated | TRUE | Voter |
| Wilhelmsson, Leif | Ericsson AB | TRUE | Voter |
| Wu, Kanke | Qualcomm Incorporated | TRUE | Voter |
| Wu, Tianyu | Apple, Inc. | TRUE | Voter |
| Wu, Wayne | MediaTek Inc. | TRUE | Potential Voter |
| Wullert, John | Peraton Labs | TRUE | Voter |
| Xiao, Bo | ZTE Corporation | TRUE | Voter |
| Xin, Liangxiao | Sony Corporation | TRUE | Voter |
| Xin, Yan | Huawei Technologies Co., Ltd | TRUE | Voter |
| Xu, Fangxin | Longsailing Semiconductor | FALSE | Non-Voter |
| Xu, Yanchao | Zeku | TRUE | Aspirant |
| Xue, Qi | Qualcomm Incorporated | TRUE | Voter |
| YAGHOOBI, HASSAN | Intel Corporation | TRUE | Voter |
| Yamada, Ryota | SHARP CORPORATION | TRUE | Voter |
| Yan, Aiguo | Zeku | TRUE | Voter |
| Yan, Zhongjiang | Northwestern Polytechnical University | TRUE | Voter |
| Yang, Bo | Huawei Technologies Co., Ltd | TRUE | Voter |
| Yang, Jay | Nokia | TRUE | Voter |
| Yang, Lin | Qualcomm Incorporated | TRUE | Voter |
| Yang, Mao | Northwestern Polytechnical University | TRUE | Voter |
| YANG, RUI | InterDigital, Inc. | TRUE | Voter |
| Yang, Steve TS | MediaTek Inc. | TRUE | Voter |
| Yang, Xun | Huawei Technologies Co., Ltd | TRUE | Voter |
| Yano, Kazuto | Advanced Telecommunications Research Institute International (ATR) | TRUE | Voter |
| Yee, James | MediaTek Inc. | TRUE | Voter |
| Yee, Peter | NSA-CSD | TRUE | Voter |
| Yi, Yongjiang | Spreadtrum Communication USA Inc. | TRUE | Voter |
| Yokoyama, Takahiro | Association of Radio Industries and Businesses (ARIB) | TRUE | Voter |
| Yong, Su Khiong | Apple, Inc. | TRUE | Voter |
| Yoon, Kangjin | Meta | FALSE | Non-Voter |
| Yu, Jian | Huawei Technologies Co., Ltd | TRUE | Voter |
| Yu, Mao | Anyka | TRUE | Voter |
| Yuan, Fangchao | Huawei Technologies Co., Ltd | TRUE | Voter |
| ZEGRAR, Salah Eddine | Istanbul Medipol University; Vestel | TRUE | Voter |
| Zeng, Yan | Huawei Technologies Co., Ltd | TRUE | Voter |
| Zhang, Hongyuan | NXP Semiconductors | TRUE | Voter |
| Zhang, Jiayi | Ofinno | TRUE | Potential Voter |
| ZHANG, JIAYIN | Huawei Technologies Co., Ltd | TRUE | Voter |
| Zhang, Yan | NXP Semiconductors | TRUE | Voter |
| Zhou, Lei | H3C Technologies Co., Limited | TRUE | Potential Voter |
| Zhou, Pei | Guangdong OPPO Mobile Telecommunications Corp.,Ltd | TRUE | Voter |
| Zia, Muhammad Furqan | Koc University; Vestel | TRUE | Potential Voter |
| Zou, Tristan | Qualcomm Incorporated | TRUE | Potential Voter |
| Zuniga, Juan Carlos | Cisco Systems, Inc. | TRUE | Potential Voter |

**Annex B : Working Group Officers**

**Working Group**

|  |  |  |
| --- | --- | --- |
| Name (Affiliation) | Position | Contact Details |
| Dorothy Stanley (HP Enterprise) | IEEE 802.11 Working Group Chair | +1( 630) 363-1389  [dstanley@ieee.org](mailto:dstanley@ieee.org) |
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| Robert Stacey (Intel Corporation) | 2nd Vice Chair (Rules and reflectors) IEEE 802 (LMSC) EC delegate | +1 (503) 712 4447 [robert.stacey@intel.com](mailto:robert.stacey@intel.com) |
| Stephen McCann (Huawei Technologies Co., Ltd) | Secretary | [stephen.mccann@ieee.org](mailto:stephen.mccann@ieee.org) |
| Peter Ecclesine (Cisco Systems, Inc.) | Co-Technical Editor | +1 (408) 710-3403 [petere@ieee.org](mailto:petere@ieee.org) |
| Robert Stacey (Intel Corporation) | Co-Technical Editor 802.11 Assigned Numbers Authority | +1 (503) 712 4447 [robert.stacey@intel.com](mailto:robert.stacey@intel.com) |

**Standing Committees**

|  |  |  |
| --- | --- | --- |
| Name (Affiliation) | Position | Contact Details |
| Jim Lansford (Qualcomm) | Wireless Next Generation (WNG) Chair | +1-719-286-8660 [jim.lansford@ieee.org](mailto:jim.lansford@ieee.org) |
| Mark Hamilton (Ruckus Wireless) | Architecture (ARC) Chair | +1 (303) 818-8472 [mark.hamilton2152@gmail.com](mailto:mark.hamilton2152@gmail.com) |
| Jon Rosdahl (Qualcomm) | Project Authorization Request (PAR) review Chair | +1 (801) 492-4023 [jrosdahl@ieee.org](mailto:jrosdahl@ieee.org) |
| Andrew Myles (Cisco) | Coexistence Standing Committee Chair | +61 418 656587 [amyles@cisco.com](mailto:amyles@cisco.com) |

**Task Groups**

|  |  |  |
| --- | --- | --- |
| Name (Affiliation) | Position | Contact Details |
| Jonathan Segev (Intel Corporation) | TGaz Chair Next Generation Positioning (NGP) | +972-54-2403587 [jonathan.segev@intel.com](mailto:jonathan.segev@intel.com) |
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| Marc Emmelmann (Koden-TI) | TGbc Chair  Broadcast Services (BCS) | [marc.emmelmann@me.com](mailto:marc.emmelmann@me.com) |
| Bo Sun (ZTE) | TGbd Chair  Next Generation V2X (NGV) | [sun.bo1@zte.com.cn](mailto:sun.bo1@zte.com.cn) |
| Alfred Asterjadhi  (Qualcomm) | TGbe Chair  Extremely High Throughput (EHT) | aasterja@qti.qualcomm.com |
| Tony Xiao Han  (Huawei Technologies Co., Ltd) | TGbf Chair  WLAN Sensing (SENS) | [tony.hanxiao@huawei.com](mailto:tony.hanxiao@huawei.com) |
| Mark Hamilton  (Ruckus/CommScope Wireless) | TGbh Chair  Random and Changing MAC address (RCM) | +1 (303) 818-8472 [mark.hamilton2152@gmail.com](mailto:mark.hamilton2152@gmail.com) |
| Carol Ansley  (Cox Communications) | TGbi Chair  Enhanced Data Privacy (EDP) | [carol@ansley.com](mailto:carol@ansley.com) |
| Michael Montemurro (Huawei Technologies Co., Ltd) | TGme Chair 802.11 revision project - P802.11REVme | [montemurro.michael@gmail.com](mailto:montemurro.michael@gmail.com) |

|  |
| --- |
|  |

**Study Groups (SG) & Topic Interest Groups (TIG)**

|  |  |  |
| --- | --- | --- |
| Name (Affiliation) | Position | Contact Details |

**Ad-Hoc Groups (AHG)**

|  |  |  |
| --- | --- | --- |
| Name (Affiliation) | Position | Contact Details |
| Hassan YAGHOOBI  (Intel) | ITU Ad-Hoc | [hassan.yaghoobi@intel.com](mailto:hassan.yaghoobi@intel.com) |

**Liaison Officials to non-IEEE 802 organizations**

|  |  |  |
| --- | --- | --- |
| Name (Affiliation) | Position | Contact Details |
| Peter Yee (Akayla) | Liaison to IETF (Internet Engineering Task Force) | [peter@akayla.com](mailto:peter@akayla.com) |
| Ian Sherlock (Texas Instruments Inc.) | Liaison to WFA (Wi-Fi Alliance) | +1-972-995-2011 [isherlock@ieee.org](mailto:isherlock@ieee.org) |

**Liaison Officials to IEEE 802 organizations**

|  |  |  |
| --- | --- | --- |
| Name (Affiliation) | Position | Contact Details |
| Jay Holcomb (Itron) | Liaison to IEEE 802.18 | +1 (509) 891-3281 [jay.holcomb@itron.com](mailto:jay.holcomb@itron.com) |
| Tuncer Baykas (Istanbul Medipol Universitesi) | Liaison to IEEE 802.19 | [tbaykas@ieee.org](mailto:tbaykas@ieee.org) |
| Tim Godfrey (Electric Power Research Institute) | Liaison to IEEE 802.24 | +1 (650) 855-8584 (office) [tim.godfrey@ieee.org](mailto:tim.godfrey@ieee.org) |
| John Kenney  (Toyota) | Liaison to IEEE 1609 | [jkenney@us.toyota-itc.com](mailto:jkenney@us.toyota-itc.com) |

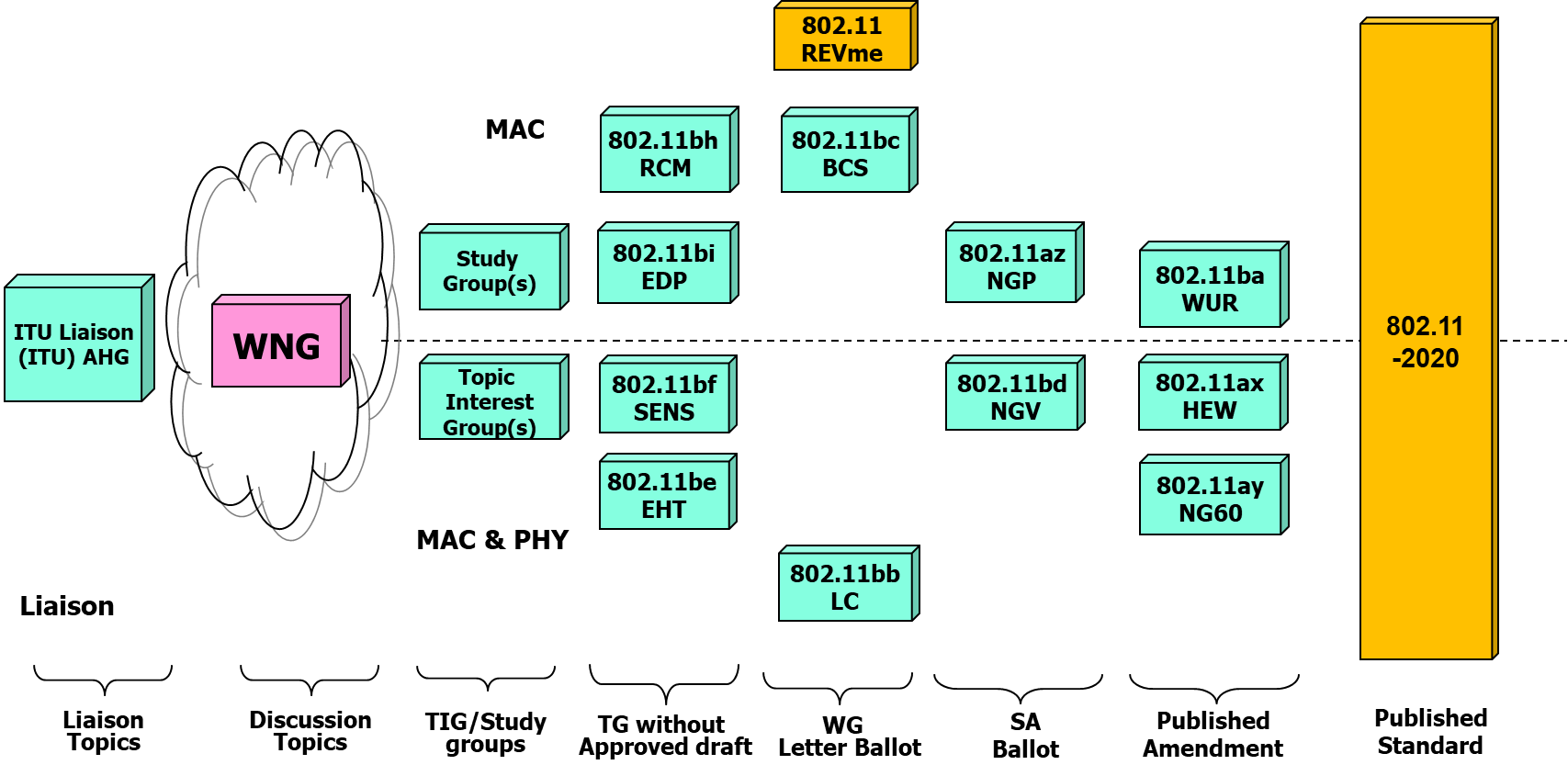
**Annex C : Minutes**

This Annex contains references to all IEEE 802.11 SC/TG/SG & Ad Hoc Committee (AHC) minutes from this meeting. Please note that they are NOT subject to the approval of these minutes, but are confirmed and approved by their individual group in the opening meeting at their next session.

|  |  |  |
| --- | --- | --- |
| WG | TE | 22-0720r0 |
| TGme | TG | 22-0782r0 |
| TGaz | TG | 22-0732r0 |
| TGbb | TG | 22-0725r0 |
| TGbc | TG | 22-0701r0 |
| TGbd | TG | 22-0778r0 |
| TGbe | TG | 22-0756r3 |
| TGbf | TG | 22-0811r0 |
| TGbh | TG | 22-0773r0 |
| TGbi | TG | 22-0801r0 |
| COEX | SC | 22-0875r0 |
| WNG | SC | 22-0736r0 |
| JTC 802 | SC | 22-0821r0 |
| ARC | SC | 22-0620r0 |

**Annex D : Revisions and Standards Pipeline**

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**IEEE 802.11 Standards Pipeline**

End.